

Dual N-channel 60 V, 9 mΩ typ., 57 A STripFET™ F7 Power MOSFET in a PowerFLAT™ 5x6 double island package

Datasheet - production data

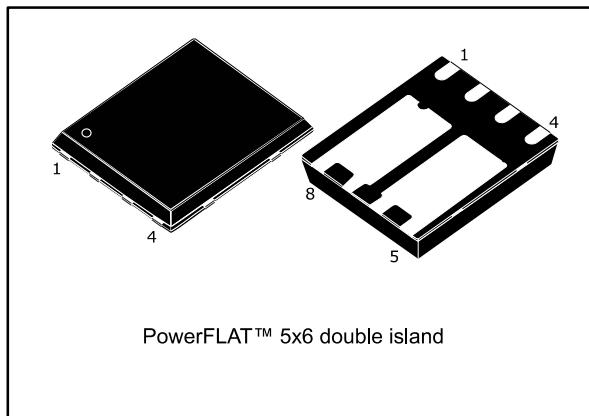
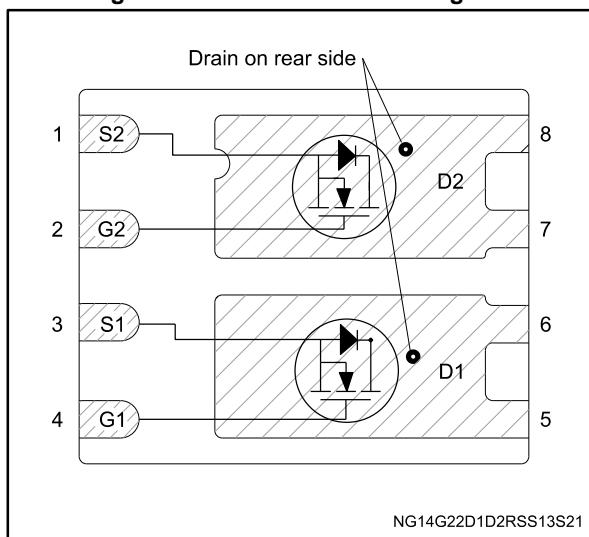


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STL50DN6F7	60 V	11 mΩ	57 A

- Among the lowest R_{DS(on)} on the market
- Excellent figure of merit (FoM)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

- Switching applications

Description

This dual N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1: Device summary

Order code	Marking	Package	Packaging
STL50DN6F7	50DN6F7	PowerFLAT™ 5x6 double island	Tape and reel

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics(curve).....	5
3	Test circuits	7
4	Package information	8
4.1	PowerFLAT 5x6 double island type R package information	9
4.2	PowerFLAT™ 5x6 packing information.....	12
5	Revision history	14

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ C$	57	A
	Drain current (continuous) at $T_C = 100^\circ C$	41	
$I_{DM}^{(1)(2)}$	Drain current (pulsed)	228	A
$I_D^{(3)}$	Drain current (continuous) at $T_{pcb} = 25^\circ C$	15	A
	Drain current (continuous) at $T_{pcb} = 100^\circ C$	11	
$I_{DM}^{(2)(3)}$	Drain current (pulsed)	60	A
P_{TOT}	Total dissipation at $T_C = 25^\circ C$	62.5	W
	Total dissipation at $T_{pcb} = 25^\circ C$	4.8	
T_J	Operating junction temperature	-55 to 175	$^\circ C$
T_{stg}	Storage temperature		

Notes:(1) This value is rated according to R_{thj-c}

(2) Pulse width limited by safe operating area.

(3) This value is rated according to $R_{thj-pcb}$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	2.4	$^\circ C/W$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	31.3	$^\circ C/W$

Notes:(1) When mounted on FR-4 board of 1inc2, 2oz Cu, $t < 10$ sec

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 4: On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		9	11	$\text{m}\Omega$

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	1035	-	pF
C_{oss}	Output capacitance		-	450	-	pF
C_{rss}	Reverse transfer capacitance		-	53	-	pF
Q_g	Total gate charge	$V_{DD} = 30 \text{ V}, I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}$ (see <i>Figure 14: "Test circuit for gate charge behavior"</i>)	-	17	-	nC
Q_{gs}	Gate-source charge		-	5.7	-	nC
Q_{gd}	Gate-drain charge		-	5.7	-	nC

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30 \text{ V}, I_D = 7.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see <i>Figure 13: "Test circuit for resistive load switching times"</i>)	-	14.5	-	ns
t_r	Rise time		-	15.3	-	ns
$t_{d(off)}$	Turn-off delay time		-	19.4	-	ns
t_f	Fall time		-	8	-	ns

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 15 \text{ A}, V_{GS} = 0 \text{ V}$ $I_{SD} = 15 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}, V_{DD} = 48 \text{ V}$ (see <i>Figure 15: "Test circuit for inductive load switching and diode recovery times"</i>)	-		1.2	V
t_{rr}	Reverse recovery time		-	26.8		ns
Q_{rr}	Reverse recovery charge		-	14.2		nC
I_{RRM}	Reverse recovery current		-	1.06		A

Notes:

⁽¹⁾Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics(curve)

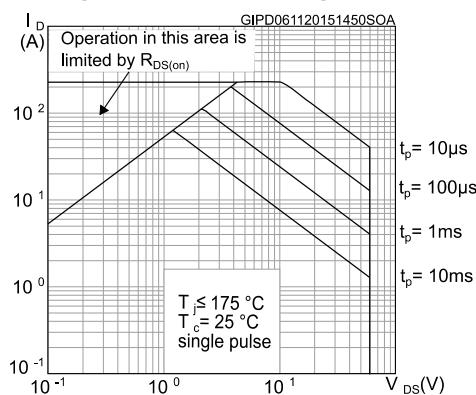
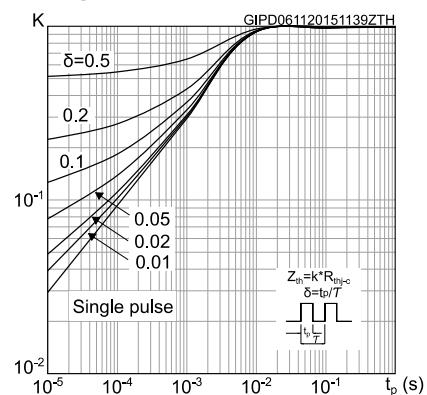
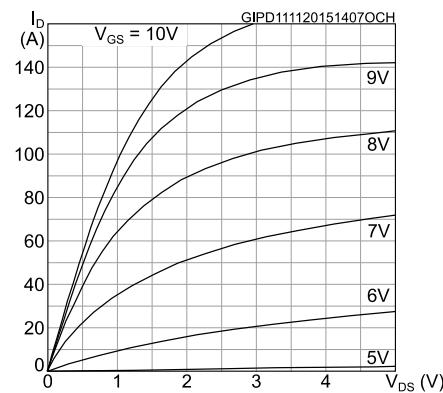
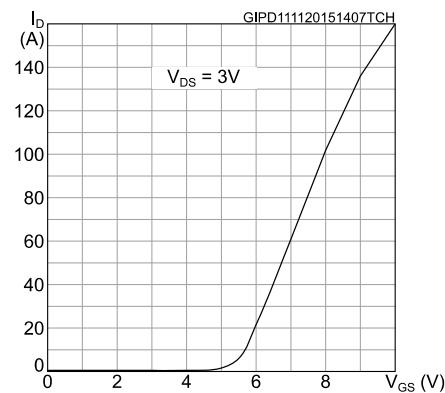
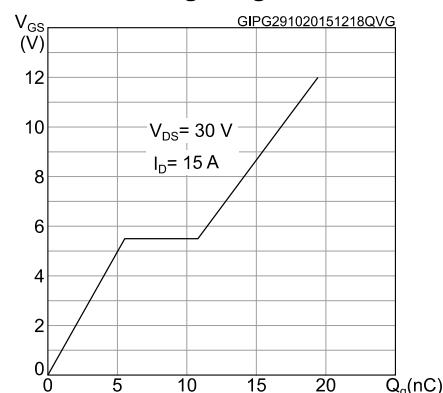
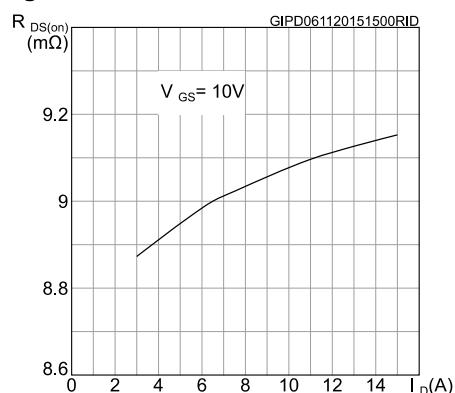
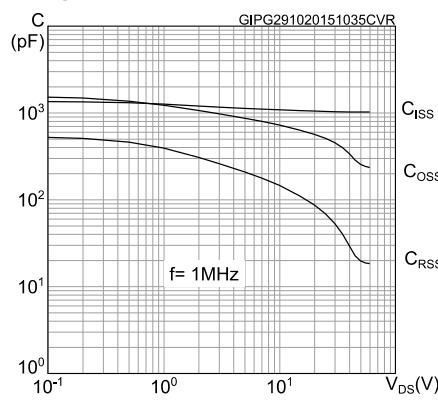
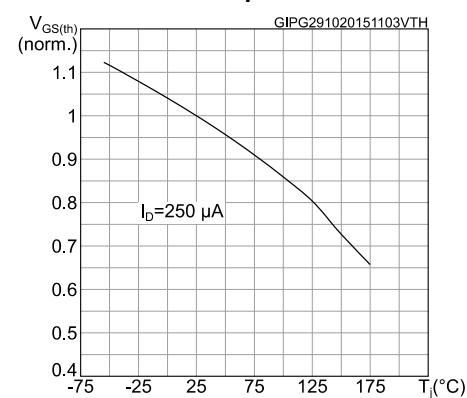
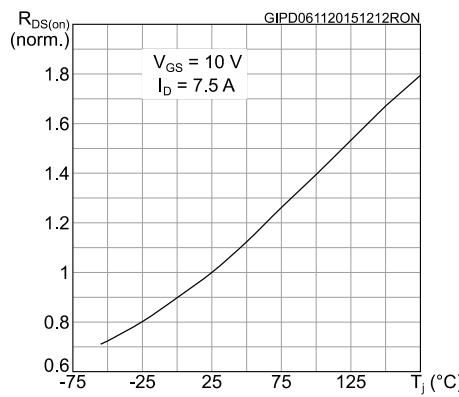
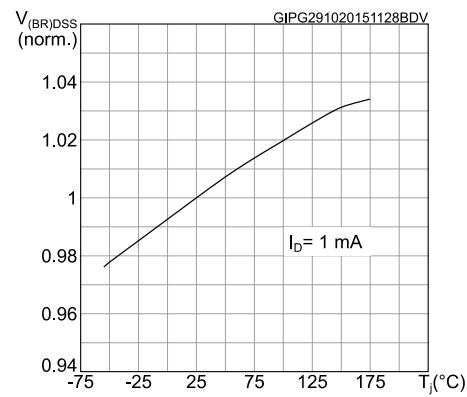
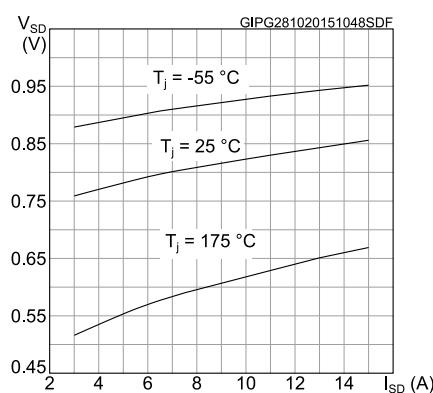
Figure 2: Safe operating area**Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

Figure 8: Capacitance variations**Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Source-drain diode forward characteristics**

3 Test circuits

Figure 13: Test circuit for resistive load switching times

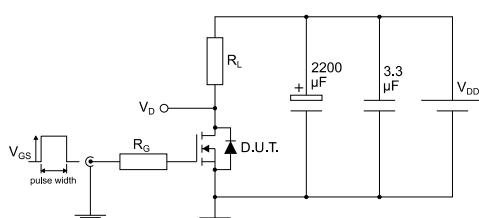


Figure 14: Test circuit for gate charge behavior

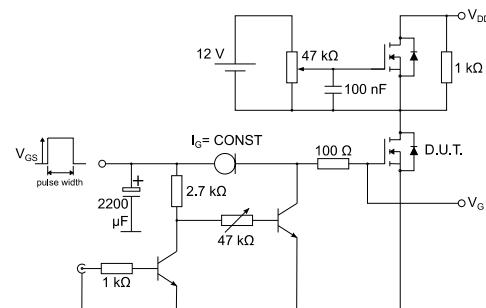


Figure 15: Test circuit for inductive load switching and diode recovery times

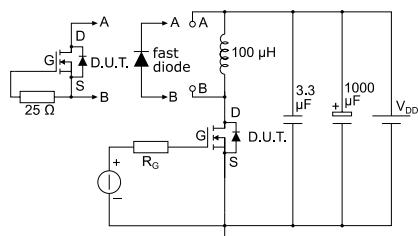


Figure 16: Unclamped inductive load test circuit

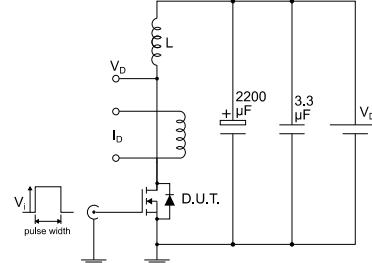


Figure 17: Unclamped inductive waveform

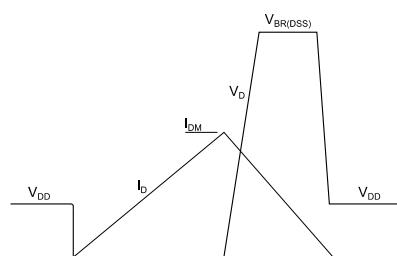
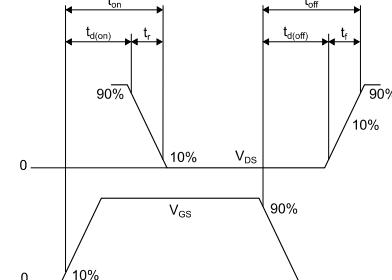


Figure 18: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 PowerFLAT 5x6 double island type R package information

Figure 19: PowerFLAT™ 5x6 double island type R package outline

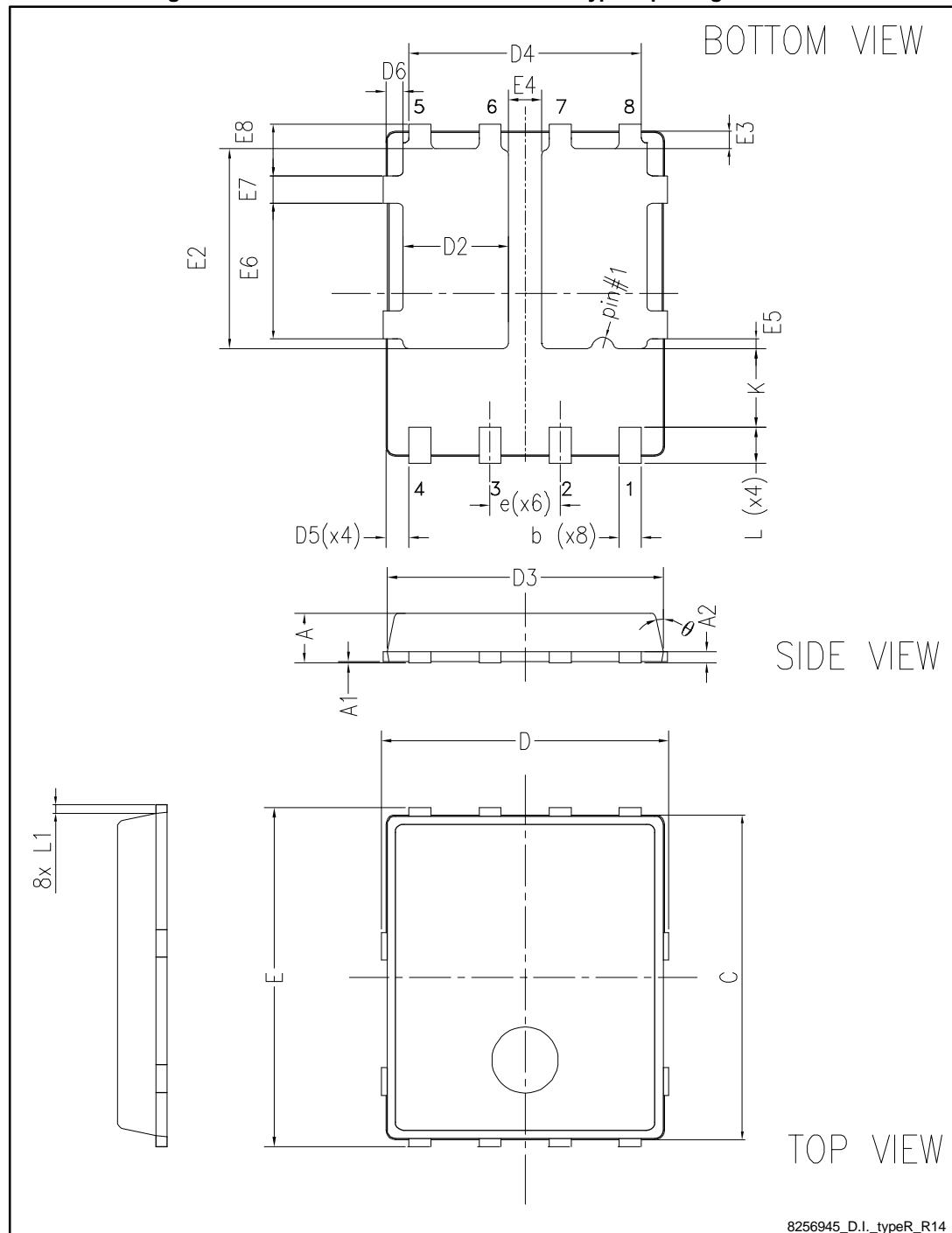
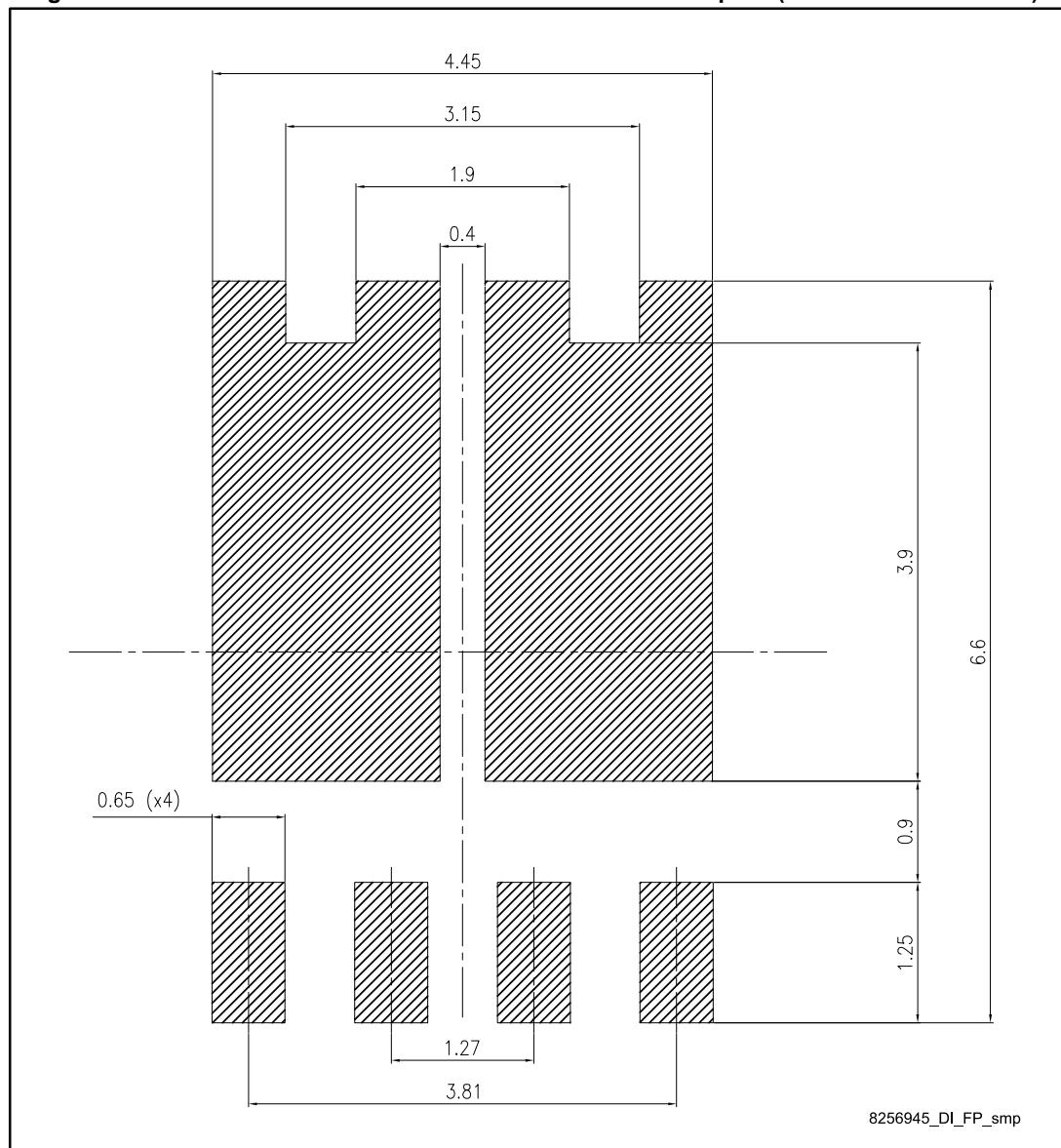


Table 8: PowerFLAT™ 5x6 double island type R mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	1.68		1.88
D3	4.80	5.00	5.20
D4	4.05	4.20	4.35
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	5.95	6.15	6.35
E2	3.50		3.70
E3	0.20	0.325	0.45
E4	0.55		0.75
E5	0.08		0.28
E6	2.35		2.55
E7	0.40		0.60
E8	0.75	0.90	1.05
L	0.60		0.80
L1	0.05	0.15	0.25
K	1.275		1.575
θ	0°		12°

Figure 20: PowerFLAT™ 5x6 double island recommended footprint (dimensions are in mm)



4.2 PowerFLAT™ 5x6 packing information

Figure 21: PowerFLAT™ 5x6 tape (dimensions are in mm)

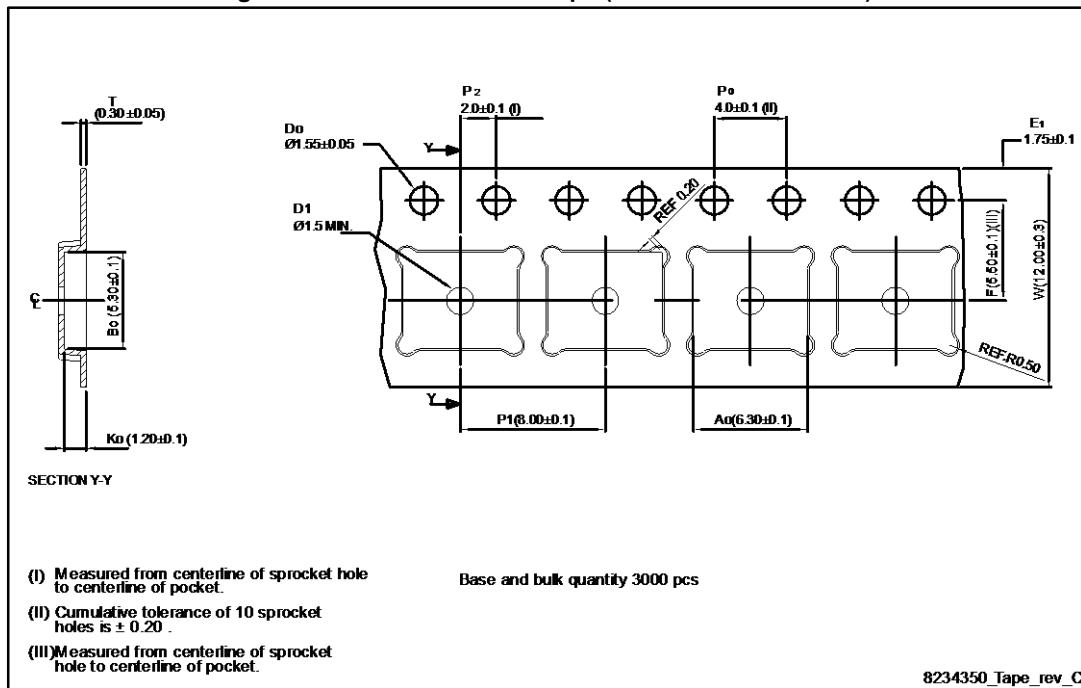


Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape

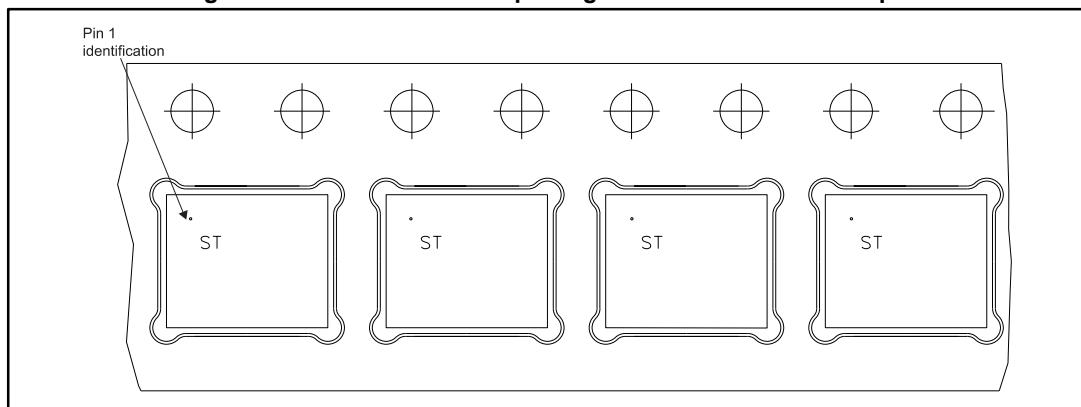
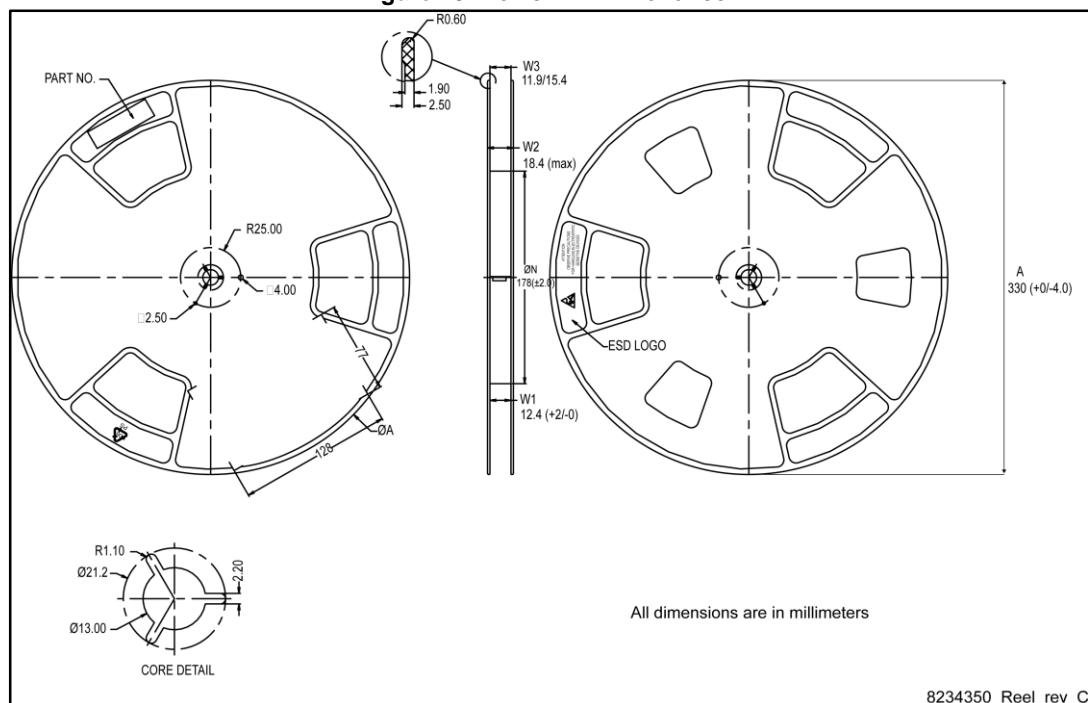


Figure 23: PowerFLAT™ 5x6 reel



5 Revision history

Table 9: Document revision history

Date	Revision	Changes
17-Jul-2015	1	First release.
13-Nov-2015	2	Document status promoted from preliminary to production data. Updated title and features in cover page. Updated Table 2: "Absolute maximum ratings" and Section 4: "Electrical characteristics" . Added Section 4.1: "Electrical characteristics(curve)" Minor text changes.

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